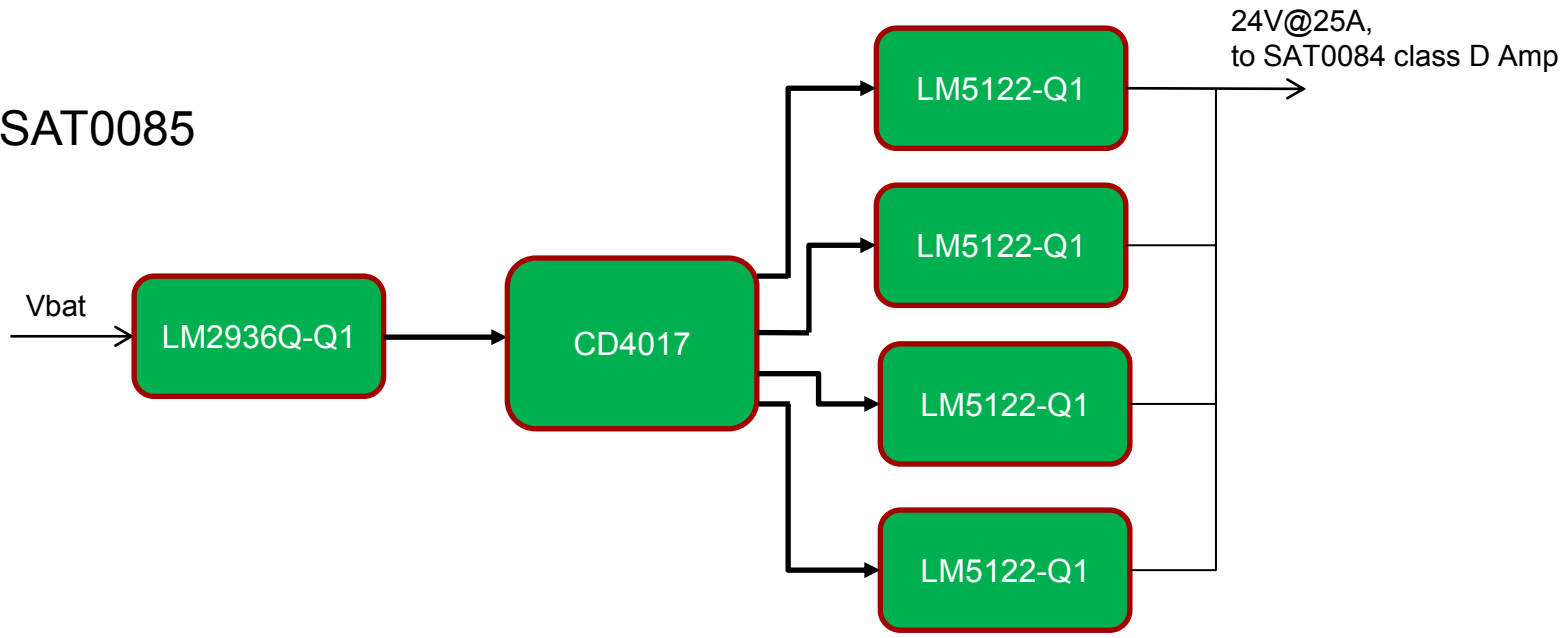
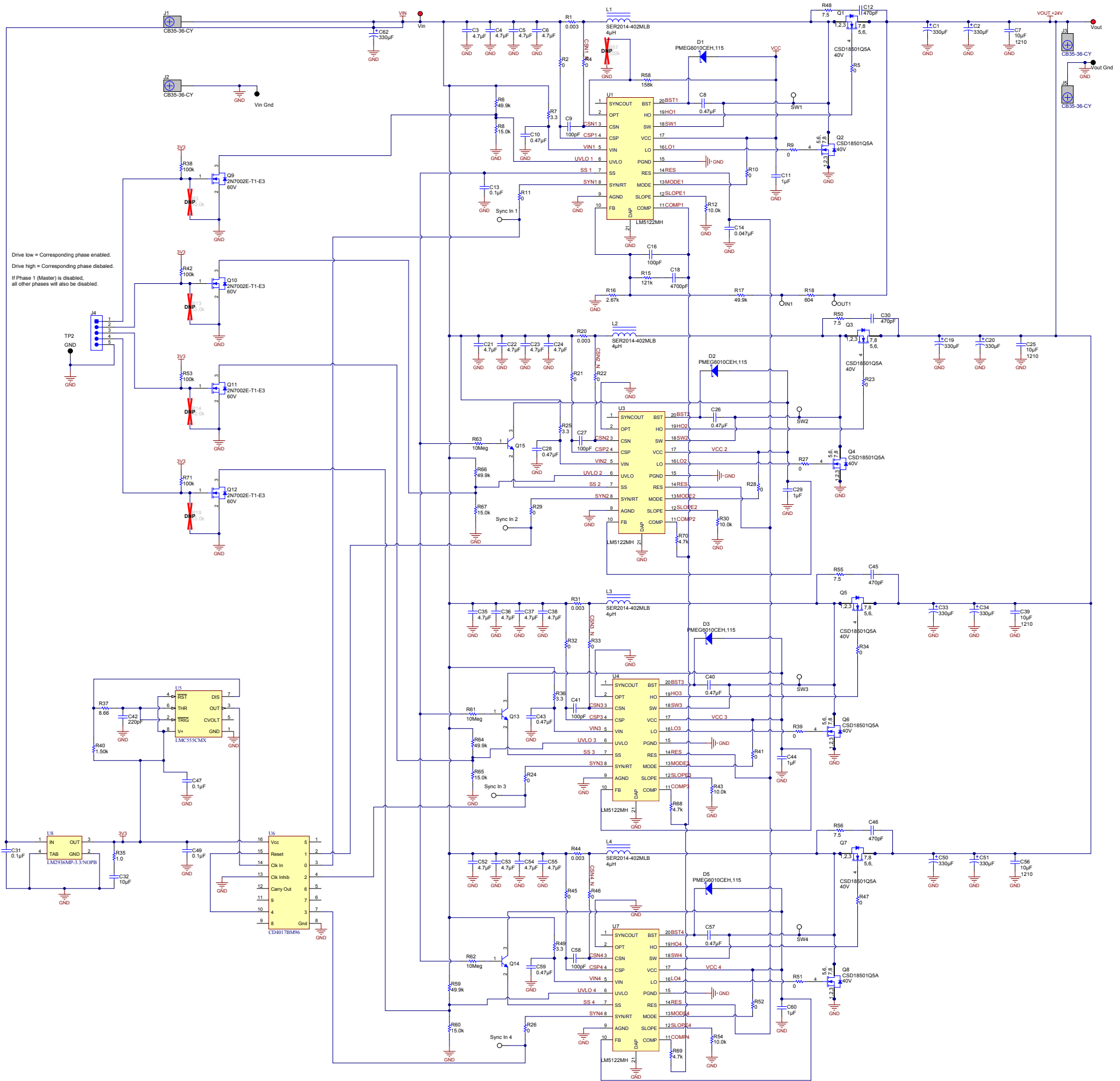


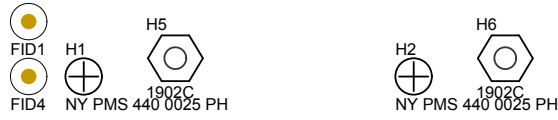
SAT0085





Drive low = Corresponding phase enabled.
 Drive high = Corresponding phase disabled.
 If Phase 1 (Master) is disabled,
 all other phases will also be disabled.

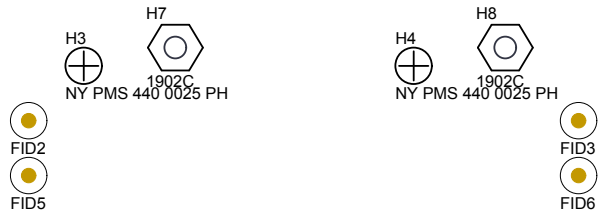
Revision History	
Revision	Notes
E1	Initial Design
A	Changes for PCB layout



PCB Number: SAT0085
PCB Rev: E1.1

PCB LOGO
Texas Instruments

PCB LOGO
ESD Susceptible



LBL1
PCB Label
Size: 0.65" x 0.20"

ZZ1
Label Assembly Note
This Assembly Note is for PCB labels only

ZZ2
Assembly Note
These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ3
Assembly Note
These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ4
Assembly Note
These assemblies must comply with workmanship standards IPC-A-610 Class 2., unless otherwise specified.

ZZ5
Assembly Note
When installing J1, J2, J3, and J5, solder AND bolt them.

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